

#### v03.0711

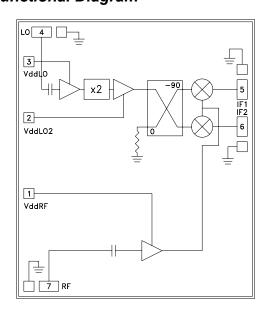
# HMC570

# GaAs MMIC I/Q DOWNCONVERTER 17 - 21 GHz

# **Typical Applications**

- The HMC570 is ideal for:
- Point-to-Point and Point-to-Multi-Point Radio
- Military Radar, EW & ELINT
- Satellite Communications

# Functional Diagram



#### Features

10 dB Conversion Gain Image Rejection: 17 dB 2 LO to RF Isolation: 35 dB Noise Figure: 3 dB Input IP3: +3 dBm Die Size: 2.33 x 2.73 x 0.10 mm

# **General Description**

The HMC570 is a compact GaAs MMIC I/Q downconverter chip which provides a small signal conversion gain of 10 dB with a noise figure of 3 dB and 17 dB of image rejection across the frequency band. The device utilizes an LNA followed by an image reject mixer which is driven by an active x2 multiplier. The image reject mixer eliminates the need for a filter following the LNA, and removes thermal noise at the image frequency. I and Q mixer outputs are provided and an external 90° hybrid is needed to select the required sideband. All data shown below is taken with the chip mounted in a 50 Ohm test fixture and includes the effects of 1 mil diameter x 20 mil length bond wires on each port. This product is a much smaller alternative to hybrid style image reject mixer downconverter assemblies.

#### Electrical Specifications, $T_A = +25^{\circ}$ C, IF = 100 MHz, LO = +4 dBm, Vdd = 3.5 Vdc\*

Parameter	Min.	Тур.	Max.	Min.	Тур.	Max.	Units
Frequency Range, RF		17.7 - 19.7			17 - 21		GHz
Frequency Range, LO	7 - 12			7 - 12			GHz
Frequency Range, IF	DC - 3.5			DC - 3.5			GHz
Conversion Gain (As IRM)	9	10		9	12		dB
Noise Figure		3			4		dB
Image Rejection	14	17		14	22		dB
1 dB Compression (Input)	-7	-4		-10	-6		dBm
2 LO to RF Isolation	35	40		30	35		dB
2 LO to IF Isolation	28	30		25	30		dB
IP3 (Input)	-5	-2		-6	+3		dBm
Amplitude Balance		0.5			0.5		dB
Phase Balance		12			4		Deg
Total Supply Current		125	165		125	165	mA

\*Data taken as IRM with external IF hybrid

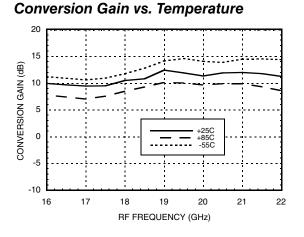
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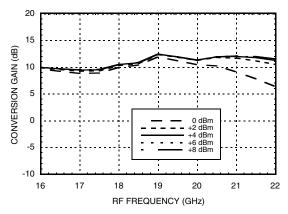
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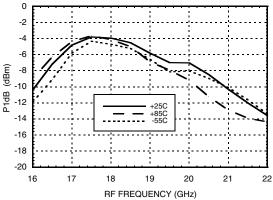
#### Data Taken As IRM With External IF Hybrid



**Conversion Gain vs. LO Drive** 



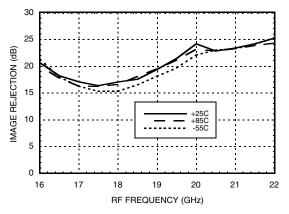
Input P1dB vs. Temperature



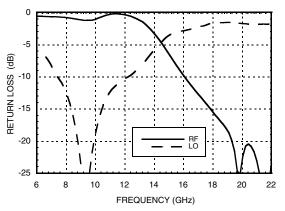
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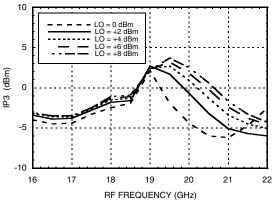
#### Image Rejection vs. Temperature



#### **Return Loss**



#### Input IP3 vs. LO Drive



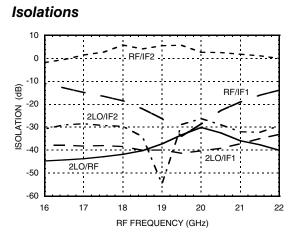


# GaAs MMIC I/Q DOWNCONVERTER 17 - 21 GHz

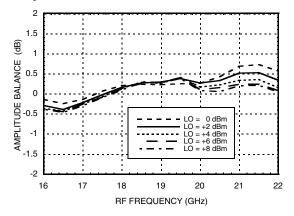
# MIXERS - I/Q RECEIVERS - CHIP

# Quadrature Channel Data Taken Without IF Hybrid

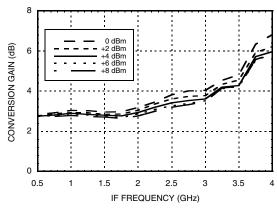
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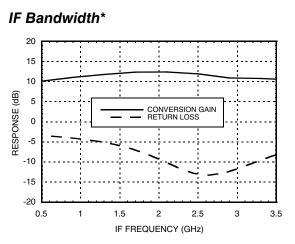


Amplitude Balance vs. LO Drive

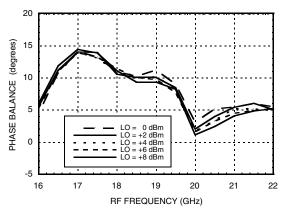


Noise Figure vs. LO Drive, LO Frequency = 8.6 GHz

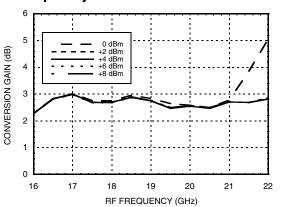




Phase Balance vs. LO Drive



Noise Figure vs. LO Drive, IF Frequency = 100 MHz



\* Conversion gain data taken with external IF hybrid, LO Frequency fixed at 8.6 GHz and RF varied

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# **MxN Spurious Outputs**

	nLO					
mRF	0	1	2	3	4	
0	xx	26	25	19	27	
1	27	26	0	25	38	
2	54	74	61	66	43	
3	xx	xx	xx	79	76	
4	xx	xx	xx	xx	xx	
RF = 18 GHz @ -20 dBm LO = 8.5 GHz @ +4 dBm Data taken without IF hybrid All values in dBc below IF power level (1RF -2LO = 1 GHz)						

#### Absolute Maximum Ratings

RF	+2 dBm
LO Drive	+ 13 dBm
Vdd	5.5V
Channel Temperature	175°C
Continuous Pdiss (T=85°C) (derate 10.2 mW/°C above 85°C)	920 mW
Thermal Resistance (R <sub>TH</sub> ) (channel to package bottom)	98.3 °C/W
Storage Temperature	-65 to +150 °C
Operating Temperature	-55 to +85 °C
ESD Sensitivity (HBM)	Class 1B



ELECTROSTATIC SENSITIVE DEVICE OBSERVE HANDLING PRECAUTIONS

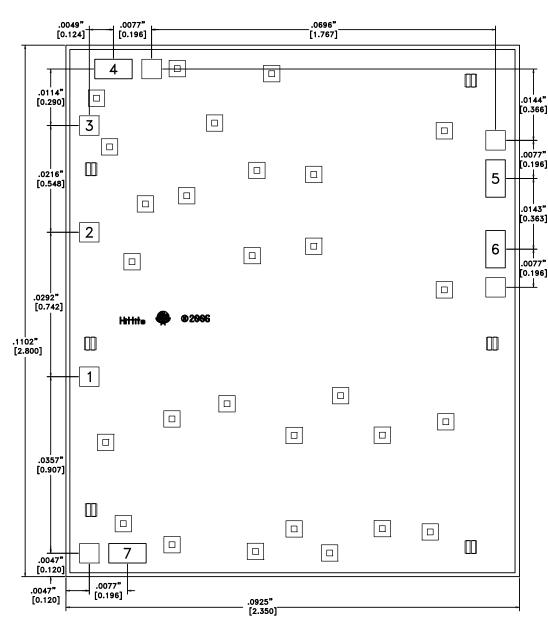
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## **Outline Drawing**



# Die Packaging Information [1]

Standard	Alternate
GP-1 (Gel Pack)	[2]

[1] Refer to the "Packaging Information" section for die packaging dimensions.

[2] For alternate packaging information contact Hittite Microwave Corporation. NOTES:

- 1. ALL DIMENSIONS ARE IN INCHES [MM]
- 2. DIE THICKNESS IS 0.004"
- 3. BOND PAD METALIZATION: GOLD
- 4. BACKSIDE METALIZATION: GOLD
- 5. BACKSIDE METAL IS GROUND
- 6. OVERALL DIE SIZE ±0.002

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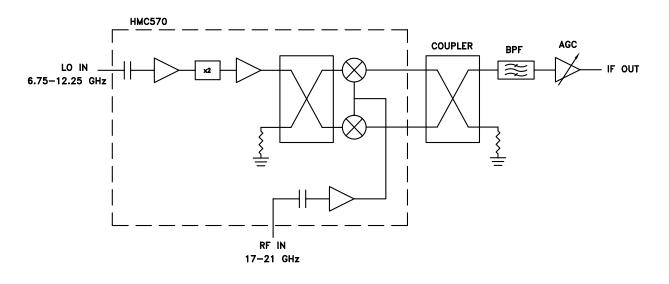
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### **Pad Descriptions**

Pad Number	Function	Description	Interface Schematic
1	VddRF	Power supply for RF LNA. External RF bypass capacitors are required.	VddRF O
2	VddLO2	Power supply for second stage of LO amplifier. External RF bypass capacitors are required.	VddLO2 O
3	VddLO	Power supply for first stage of LO amplifier. External RF bypass capacitors are required.	VddLO O
4	LO	This pad is AC coupled and matched to 50 Ohms.	
5	IF1	This pad is DC coupled. For applications not requir- ing operation to DC, this port should be DC blocked externally using a series capacitor whose value has	IF1,IF2 O
6	IF2	been chosen to pass the necessary frequency range. For operation to DC, this pad must not source /sink more than 3 mA of current or die non - function and possible die failure will result.	
7	RF	This pad is AC coupled and matched to 50 Ohms.	
	GND	The backside of the die must be connected to RF/DC ground.	

# **Typical Application**



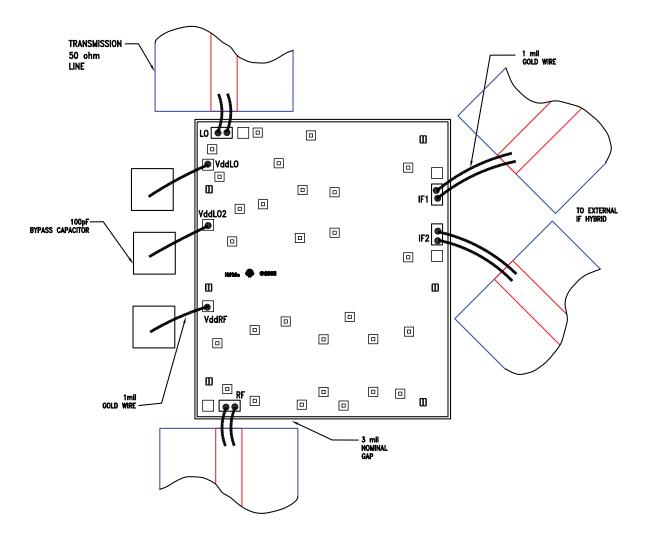
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# Assembly Drawing



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